

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings of claims in the application:

Claims 1-6 (Canceled):

Claim 7 (Previously Presented): A mixture, comprising at least one radiation-curable composition (I) and at least one pressure-sensitive adhesive (II);

wherein said mixture does not comprise an adhesive which requires an additional compound as a curing agent;

wherein the adhesive (II) comprises an adhesive composition crosslinkable by active radiant energy;

wherein the radiation-curable composition (I) comprises

(A) at least one polymerizable compound comprising two or more copolymerizable, ethylenically unsaturated groups,

(B) optionally, reactive diluents,

(C) optionally, photoinitiator, and

(D) optionally at least one coating additive.

Claim 8 (Previously Presented): A mixture as claimed in claim 7, wherein the radiation-curable composition (I) comprises

40 – 100% by weight of at least one polymerizable compound comprising two or more copolymerizable, ethylenically unsaturated groups (A),

0 – 60% by weight of reactive diluents (B),

0 – 20% by weight of photoinitiator (C), and

0 – 50% by weight of at least one coating additive (D)

wherein (A), (B), (C) and (D) together make up 100% by weight.

Claim 9 (Previously Presented): A mixture as claimed in claim 7, comprising compounds (A) comprising carbonate or urethane (meth)acrylates or carbonate or urethane vinyl ethers.

Claim 10 (Previously Presented): A mixture as claimed in claim 7, comprising at least one polymer-analogously modified copolymer as compound (A).

Claim 11 (Previously Presented): A mixture, comprising:
90 – 99.9% by weight of at least one radiation-curable composition (I); and
0.1 – 10% by weight of at least one pressure-sensitive adhesive (II);
wherein said mixture does not comprise an adhesive which requires an additional compound as a curing agent;
wherein the adhesive (II) comprises an adhesive composition crosslinkable by active radiant energy.

Claim 12 (Canceled):

Claim 13 (Previously Presented): A method of coating a substrate, comprising:
coating a substrate with a coating material comprising a mixture, thereby obtaining a coated substrate;
thermally treating said coated substrate, and
curing said coating material with active radiant energy;

wherein said mixture comprises at least one radiation-curable composition (I) and at least one pressure-sensitive adhesive (II);

wherein said mixture does not comprise an adhesive which requires an additional compound as a curing agent.

Claim 14 (Previously Presented): A method as claimed in claim 13, wherein said active radiant energy is light of wavelength ranging from 150 to 700 nm.

Claim 15 (Previously Presented): A method as claimed in claim 13, wherein the thermal treatment is carried out at between 40 and 120°C.

Claim 16 (Canceled).

Claim 17 (Previously Presented): A method of coating a substrate, comprising:
coating a substrate with a coating material comprising a mixture, thereby obtaining a coated substrate;

wherein said substrate is plastic, glass or metal;

wherein said mixture comprises at least one radiation-curable composition (I) and at least one pressure-sensitive adhesive (II);

wherein said mixture does not comprise an adhesive which requires an additional compound as a curing agent;

wherein the adhesive (II) comprises an adhesive composition crosslinkable by active radiant energy;

wherein the radiation-curable composition (I) comprises

- (A) at least one polymerizable compound comprising two or more copolymerizable, ethylenically unsaturated groups,
- (B) optionally, reactive diluents,
- (C) optionally, photoinitiator, and
- (D) optionally at least one coating additive.

Claim 18 (Previously Presented): A method of coating a substrate, comprising:
coating a substrate with a coating material comprising a mixture, thereby obtaining a coated substrate;

wherein said substrate is metal foil, plastic film or a composite of metal foil and plastic film;

wherein said mixture comprises at least one radiation-curable composition (I) and at least one pressure-sensitive adhesive (II);

wherein said mixture does not comprise an adhesive which requires an additional compound as a curing agent;

wherein the adhesive (II) comprises an adhesive composition crosslinkable by active radiant energy;

wherein the radiation-curable composition (I) comprises

- (A) at least one polymerizable compound comprising two or more copolymerizable, ethylenically unsaturated groups,
- (B) optionally, reactive diluents,
- (C) optionally, photoinitiator, and
- (D) optionally at least one coating additive.

Claim 19 (Previously Presented): A mixture as claimed in claim 7, wherein the adhesive (II) comprises at least one acrylic adhesive.

Claim 20 (Previously Presented): A mixture as claimed in claim 7, wherein the adhesive has a glass transition temperature T_g of between -60 and -10°C .

Claim 21 (Canceled):

Claim 22 (Previously Presented): A mixture as claimed in claim 7, wherein the adhesive composition crosslinkable by active irradiation of energy has a glass transition temperature T_g of between -60 and $+10^{\circ}\text{C}$.

Claim 23 (Previously Presented): A mixture as claimed in claim 7, wherein the adhesive composition crosslinkable by active irradiation of energy has a molar weight of between 200 000 and 1 500 000 g/mol.

Claim 24 (Previously Presented): A mixture as claimed in claim 11, wherein the adhesive (II) comprises at least one acrylic adhesive.

Claim 25 (Previously Presented): A mixture as claimed in claim 11, wherein the adhesive has a glass transition temperature T_g of between -60 and -10°C .

Claim 26 (Canceled):

Claim 27 (Previously Presented): A mixture as claimed in claim 11, wherein the adhesive composition crosslinkable by active irradiation of energy has a glass transition temperature T_g of between -60 and $+10^\circ\text{C}$.

Claim 28 (Canceled):

Claim 29 (Previously Presented): A mixture, comprising:

90 – 99.9% by weight of at least one radiation-curable composition (I); and

0.1 – 10% by weight of at least one pressure-sensitive adhesive (II);

wherein said mixture does not comprise an adhesive which requires an additional compound as a curing agent;

wherein the adhesive composition crosslinkable by active irradiation of energy has a molar weight of between 200 000 and 1 500 000 g/mol.